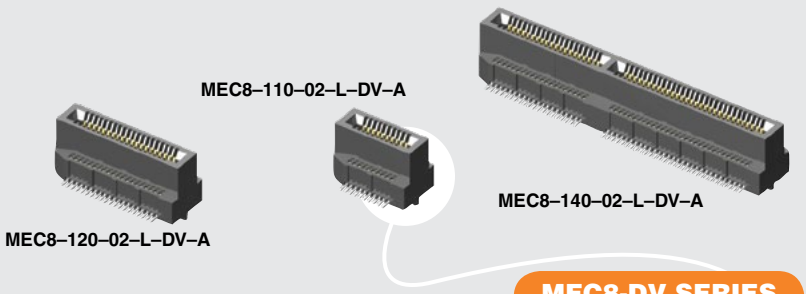


(0.80 mm) .0315"

MEC8-DV SERIES

VERTICAL MICRO EDGE CARD SOCKET

SPECIFICATIONS

For complete specifications and recommended PCB layouts see www.samtec.com?MEC8-DV

Insulator Material:
Black LCP
Contact Material:
Phosphor Bronze
Plating:
Au or Sn over
50 µ" (1.27 µm) Ni
Operating Temp Range:
-55 °C to +125 °C
Insertion Depth:
(4.22 mm) .166" to
(5.66 mm) .223"
Current Rating:
1.8 A per pin
(4 adjacent pins powered)
Voltage Rating:
185 VAC
RoHS Compliant:
Yes

PROCESSING

Lead–Free Solderable:
Yes
SMT Lead Coplanarity:
(0.10 mm) .004" max (10-50)
(0.15 mm) .006" max (60-70)*
*(.004" stencil solution may be available; contact IPG@samtec.com)

RECOGNITIONS

For complete scope of recognitions see www.samtec.com/quality

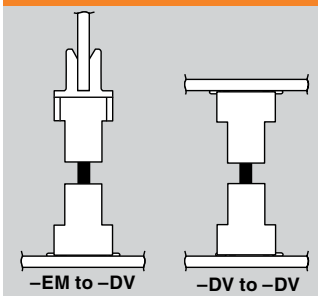
FILE NO. E111594

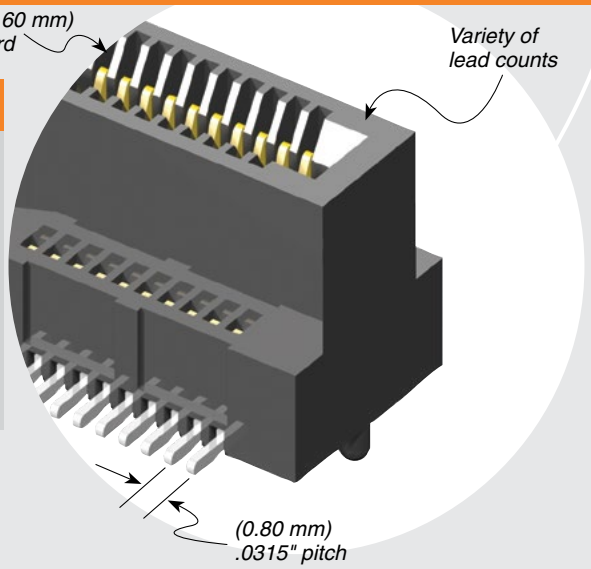
ALSO AVAILABLE
(MOQ Required)

- 1 mm mating card thickness option
- Locking clip (Manual placement required)

Mates with:
(1.60 mm) .062" thick card

APPLICATIONS





HIGH-SPEED CHANNEL PERFORMANCE

MEC8-DV

Rating based on Samtec reference channel. For full SI performance data visit Samtec.com or contact SIG@samtec.com

25 Gbps

MEC8	–	1	–	02	–		–	DV	–	
		POSITIONS PER ROW				PLATING OPTION				OTHER OPTION

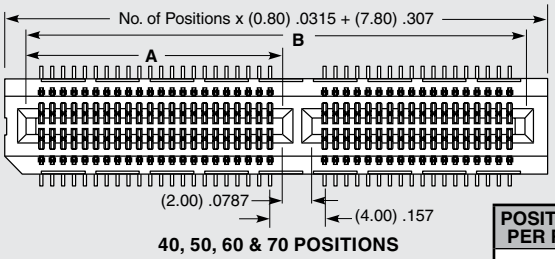
10, 20, 30, 40, 50, 60, 70

–L
= 10 µ" (0.25 µm) Gold on contact, Matte Tin on tail

–A
= Alignment Pin

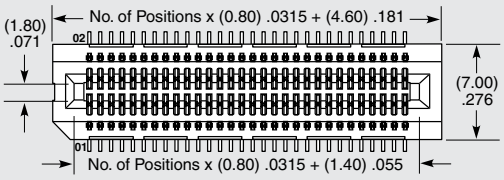
–K
= (5.50 mm) .217" DIA Polyimide Pick & Place Pad

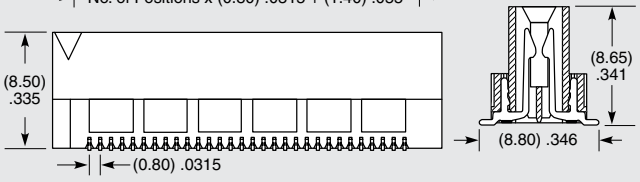
–TR
= Tape & Reel



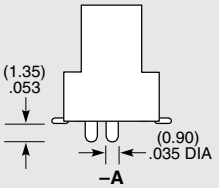
40, 50, 60 & 70 POSITIONS

POSITIONS PER ROW	A	B
40	(18.90) .744	(36.60) 1.441
50	(22.90) .902	(44.60) 1.756
60	(26.90) 1.059	(52.60) 2.071
70	(30.90) 1.217	(60.60) 2.386





10, 20 & 30 POSITIONS



–A OPTION

OTHER SOLUTIONS

- Right-angle
- Edge Mount
- See samtec.com?MEC8-RA or samtec.com?MEC8-EM

Notes:
While optimized for 50 Ω applications, this connector with alternative signal/ground patterns may also perform well in certain 75 Ω applications. Some sizes, styles and options are non-standard, non-returnable.